Solderability Confirmed visually.	40 % to 70 %(Note3) ange t 1 A
Rating Coperating humidity range 20 % to 80 % (Notes 2) Storage humidity range Voltage 150 V AC (DC) Curren Applicable Connector DF13-*S-1.25C Applicable Contact Specifications Specifications Item Test method Construction General examination Visually and by measuring instrument. Acc Marking Confirmed visually. Electric characteristics Contact resistance 100 m A (DC or 1000 Hz). 30 m South of the sistance 100 V DC. 500 South of the sistance 100 m South of the sistance South of the si	## 40 % to 70 %(Note3) ### 1
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Shock 490 m/s² duration of pulse 11 ms at 3 times for 3 directions.	No damage, crack or looseness of parts.
Shock 490 m/s² duration of pulse 11 ms at 3 times for 3 directions. Environmental characteristics Rapid change of temperature	No electrical discontinuity of 1μs. X -
directions. Environmental characteristics Rapid change of temperature	No damage, crack or looseness of parts.
Rapid change of temperature Temperature -55 → 5 to 35 → 85 → 5 to 35 °c Time 30 → 10 to 15 → 30 → 10 to 15 min. 2 Image: Ima	X -
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